| © Copyright 20                    | omposition De<br>005. IPC, Bannock<br>1d Pan-American c  | burn, Illinois. A                      | ll rights reserved nations. | under both    | This docume<br>level parts, t                                     | ent is a declaration e  | on of the su                          | ibstances v<br>s all lower | within the manufacture<br>level materials for v | urer listed<br>which the        | item. Note: i<br>nanufacturer | f the item is an as<br>has engineering | sembly with low responsibility. |  |
|-----------------------------------|--|--|-----------------------------|---------------|---|-------------------------|---------------------------------------|----------------------------|---|---------------------------------|-------------------------------|--|---------------------------------|--|
|                                   | IPC Web Site for Information on IPC-1752 Standard Form Type   http://www.ipc.org/IPC-175x Distribute |  |                             | *             | Declaration Class *<br>Class 6 - RoHS Yes/No, Homogeneous Materia |                         |                                       |                            |   | als and Mfg Information         |                               |  |                                 |  |
| Supplier Information              |  |  |                             |               |   |                         |                                       |                            |   |                                 |                               |  |                                 |  |
| Company name*                     | Company uni  | Company unique ID                      |                             |               | Unique ID Authority   |                         |                                       |                            | Respon  | Response Date*                  |                               |  |                                 |  |
| nsemi                             |  |  |                             |               |   |                         |                                       |                            | 2024-0  | 2024-05-15                      |                               |  |                                 |  |
| Contact Name Title - Co           |  |  | e - Contact                 |               |   | Phone - Contact*        |                                       |                            |   | Email ·                         | Email - Contact*              |  |                                 |  |
| Product-Env-Stewards              | Product Enviro Compliance  |  |                             |               | NA  |                         |                                       |                            | Produ   | Product-Env-Stewards@onsemi.com |                               |  |                                 |  |
| Authorized Representative* Tit    |  |  | Title - Representative      |               |   | Phone - Representative* |                                       |                            |   | Email ·                         | Email - Representative*       |  |                                 |  |
| Product-Env-Stewards              | Product Enviro Compliance  |  |                             |               | NA  |                         |                                       |                            | Produ   | Product-Env-Stewards@onsemi.com |                               |  |                                 |  |
| Requester Item Number             | Mfr Iten   | n Number                               | Number Mfr Item Name        |               |   | Effective Date          | Version                               | М                          | Ianufacturing Site                              |                                 | Weight*                       | UOM                                    | Unit Type                       |  |
|                                   | NVMFS<br>AFT1G   | NVMFS5C612NLWF NFET SO8FL 60V<br>AFT1G |                             | )V            | 202   |                         |                                       | М                          | MY1   |                                 | 107.2528                      | mg                                     | Each                            |  |
| Aanufacturing Proccess Info       | rmation  |  |                             |               |   |                         |                                       |                            |   |                                 |                               |  |                                 |  |
| Terminal Plating / Grid Arr       | ay Material  | terial Terminal Base Alloy             |                             | J-STD-020 MSL | )20 MSL Rating  |                         | Peak Process Body Temperature Max Tin |                            | e Max Time at Pea                               | k Tempera                       | ture Numb                     | er of Reflow Cyc                       | cles                            |  |
| Matte Tin (Sn) - annealed CU      |  | CU Alloy                               | Alloy 1                     |               |   | 260                     | 260 C                                 |                            | 30  | secc                            |                               | seconds 3                              |                                 |  |
| omments                           |  |  |                             |               |   |                         |                                       |                            |   |                                 |                               |  |                                 |  |
| vel 1 - maximum time at peak temp | erature during so  | dering is 10-3                         | 0 seconds                   |               |   |                         |                                       |                            |   |                                 |                               |  |                                 |  |
| or more information regarding mat | erial composition  | please refer to                        | page 3                      |               |   |                         |                                       |                            |   |                                 |                               |  |                                 |  |

| RoHS Material Composition Declaration  |   |  |   | Declaration Type *  | Detailed  |  |  |  |  |  |
|--|---|--|---|---|---|--|--|--|--|--|
| Directive 2015/863/EU amending RoHS<br>Directive 2011/65/EU  | RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP). |  |   |   |   |  |  |  |  |  |
| cadmium, hexavalentchromium, polybromina<br>contains a RoHS restricted substance inexces<br>encompass all such components. Supplier cer<br>as of the date that Supplier completes this for<br>Company acknowledges that Supplier may h<br>independently verified information provided<br>certification in this paragraph. If the Company | ated biphenyls and/or polybrominated dip<br>s of an applicable quantity limit, please in<br>iffies that it gathered the information it pr<br>m.Supplier acknowledges that Company<br>ave relied on informationprovided by oth<br>by others, Supplier agrees that, at a minir<br>and the Supplier enter into a written agr<br>esource of the Supplier's liability and the  | henyl ethers (each a "RoHS restricted substa<br>ndicate below which, if any, RoHS exemption<br>ovides in this form using appropriate methoo<br>will rely on this certification in determining<br>ers in completing this form, and that Supplie<br>num, itssuppliers have provided certification<br>eement with respect to the identified part, the<br>Company's remedies for issues that arise reg | nce") in exco<br>n you believe<br>ls to ensure i<br>the compliar<br>r may not ha<br>s regarding t<br>terms and co | e may apply. If the part is an assembly with low<br>s accuracy and that such information is true an<br>ce of its products with European Union member<br>de independently verified such information. Ho<br>neir contributions to the part, and those certifica | ove. If a homogeneous material within the part<br>er level components, the declaration shall<br>d correct to the best of its knowledge and belief,<br>er state laws that implement the RoHS Directive.<br>wever, in situations where Supplier has not<br>ations are at least as comprehensive as the<br>anty rights and/or remedies provided as part of |  |  |  |  |  |
| RoHS Declaration * 4 - Item(   | s) does not contain RoHS restricted subst   | ances per the definition above except for sele   | ected exempt  | ions Supplier Acceptance  | * Accepted  |  |  |  |  |  |
| Exemption: 7a: Lead in high melting temp   | erature type solders (i.e. lead based sol   | der alloys containing 85% by weight or m   | ore lead).  |   |   |  |  |  |  |  |
| Exemption List Version   | EL-2011/534/EU  |  |   |   |   |  |  |  |  |  |
| Declaration Signature  |   |  |   |   |   |  |  |  |  |  |
| Instructions: Complete all of the required<br>Requester) and click on Submit Form to h   |   |  | e drop-dowi   | a. This will display the signature area. Digita   | lly sign the declaration (if required by the  |  |  |  |  |  |
| Supplier Digital Signature   | astislav Drska  | Le   |   |   |   |  |  |  |  |  |

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

| Homogeneous Material | Weight  | Unit of Measure | Level    | Substance               | CAS              | Exempt | Weight  | Unit of Measure |
|----------------------|---------|-----------------|----------|-------------------------|------------------|--------|---------|-----------------|
| Clip                 | 13.512  | mg              | Supplier | Zinc (Zn)               | 7440-66-6        |        | 0.0162  | mg              |
|                      |         |                 | Supplier | Iron (Fe)               | 7439-89-6        |        | 0.3175  | mg              |
|                      |         |                 | Supplier | Copper (Cu)             | 7440-50-8        |        | 13.1742 | mg              |
|                      |         |                 | Supplier | Phosphorus (P)          | 7723-14-0        |        | 0.0041  | mg              |
| Die                  | 0.727   | mg              | Supplier | Silicon (Si)            | 7440-21-3        |        | 0.727   | mg              |
| Die Attach Solder    | 1.4993  | mg              | Supplier | Silver (Ag)             | 7440-22-4        |        | 0.0375  | mg              |
|                      |         |                 | А        | Lead (Pb)               | 7439-92-1        | 7a     | 1.3869  | mg              |
|                      |         |                 | Supplier | Tin (Sn)                | 7440-31-5        |        | 0.075   | mg              |
| Lead Frame           | 42.5398 | mg              | Supplier | Silver (Ag)             | 7440-22-4        |        | 0.0255  | mg              |
|                      |         |                 | Supplier | Iron (Fe)               | 7439-89-6        |        | 0.0425  | mg              |
|                      |         |                 | Supplier | Copper (Cu)             | 7440-50-8        |        | 42.459  | mg              |
|                      |         |                 | Supplier | Phosphorus (P)          | 7723-14-0        |        | 0.0128  | mg              |
| Mold Compound-Black  | 48.7198 | mg              |          | Epoxy resin             | proprietary data |        | 3.654   | mg              |
|                      |         |                 | Supplier | Phenolic Resin          | Proprietary Data |        | 1.218   | mg              |
|                      |         |                 | Supplier | Silica Amorphous (SiO2) | 7631-86-9        |        | 3.654   | mg              |
|                      |         |                 | Supplier | Carbon Black (C)        | 1333-86-4        |        | 0.2436  | mg              |
|                      |         |                 | Supplier | Fused Silica (SiO2)     | 60676-86-0       |        | 39.9502 | mg              |
| Plating              | 0.2183  | mg              | Supplier | Tin (Sn)                | 7440-31-5        |        | 0.2183  | mg              |
| Wire Bond - Cu       | 0.0366  | mg              | Supplier | Copper (Cu)             | 7440-50-8        |        | 0.0366  | mg              |